

B2 10. (amended) The wiring substrate according to claim 6, wherein the acid anhydride curing agent, before embedding, has a viscosity at  $25^{\circ}\text{C} \pm 1^{\circ}\text{C}$  of not higher than  $170 \text{ mPa} \cdot \text{s}$ .

B3 12. (amended) The wiring substrate according to claim 6, wherein the filler contains at least one inorganic filler.

**IN THE ABSTRACT:**

Please delete the present Abstract of the Disclosure and replace it with the following new Abstract of the Disclosure.

**Abstract of the Disclosure**

B4 A wiring substrate includes (1) an insulating substrate having an opening, or a core substrate and a build-up layer wherein at least one of the core substrate and the build-up layer has an opening, (2) at least one electronic part disposed in the opening, and (3) an embedding resin comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity of not higher than  $85 \text{ Pa} \cdot \text{s}$  in a shear rate of  $8.4 \text{ s}^{-1}$  after allowing to stand for 24 hours at  $25^{\circ}\text{C} \pm 1^{\circ}\text{C}$ .